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March 2015

FDD8451

N-Channel PowerTrench[®] MOSFET 40V, 28A, $24m\Omega$

Features

- Max $r_{DS(on)} = 24m\Omega$ at $V_{GS} = 10V$, $I_D = 9A$
- Max $r_{DS(on)} = 30m\Omega$ at $V_{GS} = 4.5V$, $I_D = 7A$
- Low gate charge
- Fast Switching
- High performance trench technology for extremely low r_{DS(on)}
- RoHS compliant

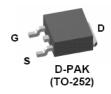


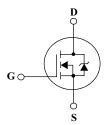
General Description

This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, fast switching speed and extremely low $r_{\text{DS}(\text{on})}.$

Application

- DC/DC converter
- Backlight inverter





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DS}	Drain to Source Voltage	40	V
V_{GS}	Gate to Source Voltage	±20	V
	Drain Current -Continuous @T _C =25°C	28	
I _D	-Continuous @T _A =25°C (Note 1a	9	Α
	-Pulsed	78	
E _{AS}	Single Pulse Avalanche Energy (Note 3) 20	mJ
P_{D}	Power Dissipation	30	W
T _J , T _{STG}	Operating and Storage Temperature	-55 to 150	°C

Thermal Characteristics

$R_{ heta JC}$	Thermal Resistance, Junction to Case		4.1	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	96	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD8451	FDD8451	D-PAK(TO-252)	13"	16mm	2500 units

©2009 Fairchild Semiconductor Corporation FDD8451 Rev. 1.2

Units

Max

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

Parameter

Off Characteristics							
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	40			V	
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 250μA, referenced to 25°C		33.5		mV/°C	
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 32V, V _{GS} = 0V			1	μА	
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			±100	nA	

Test Conditions

Min

Тур

On Characteristics

Symbol

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1	2.1	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250μA, referenced to 25°C		-5.7		mV/°C
r _{DS(on)}	Drain to Source On Resistance	V _{GS} = 10V, I _D = 9A		19	24	
		$V_{GS} = 4.5V, I_D = 7A$		23	30	m_{Ω}
		V _{GS} = 10V, I _D = 9A T _J = 150°C		32	41	11152
9 _{FS}	Forward Transcondductance	$V_{DS} = 5V, I_{D} = 9A$		29		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V - 20V V - 0V	780	990	pF
Coss	Output Capacitance	V _{DS} = 20V, V _{GS} = 0V, f = 1MHz	112	150	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1101112	72	110	pF
R _a	Gate Resistance	f = 1MHz	1.1		Ω

Switching Characteristics

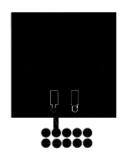
t _{d(on)}	Turn-On Delay Time		7	14	ns
t _r	Rise Time	$V_{DD} = 20V, I_D = 9A$ $V_{GS} = 10V, R_{GEN} = 6\Omega$	3	10	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = 10V, R _{GEN} = 052	19	34	ns
t _f	Fall Time		2	10	ns
Q_g	Total Gate Charge at 10V		16	20	nC
Q_g	Total Gate Charge at 5V	V_{DS} = 20V, I_{D} = 9A V_{GS} = 10V	8.6	11	nC
Q_{gs}	Gate to Source Gate Charge		2.5		nC
Q_{gd}	Gate to Drain "Miller" Charge		3.7		nC

Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0V$, $I_S = 9A$	0.87	1.2	V
t _{rr}	Reverse Recovery Time	I _F = 9A, di/dt = 100A/μs	25	38	ns
Q _{rr}	Reverse Recovery Charge	$I_F = 9A$, di/dt = 100A/ μ s	19	29	nC

Notes:

1: R_{0,IA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0,IC} is guaranteed by design while R_{0,IA} is determined by the user's board design.



40 °C/W when mounted on a 1 in² pad of 2 oz copper



96 °C/W when mounted on a minimum pad

- 2: Pulse Test: Pulse Width < 300 μ s, Duty cycle < 2.0%. 3: Starting T $_J$ = 25 °C, L = 0.1 mH, I $_{AS}$ = 20 A, V $_{DD}$ = 36 V, V $_{GS}$ = 10 V.

Typical Characteristics T_J = 25°C unless otherwise noted

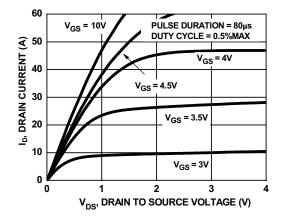


Figure 1. On Region Characteristics

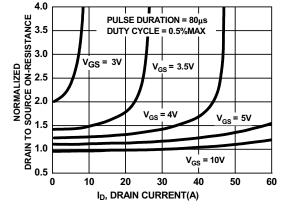


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

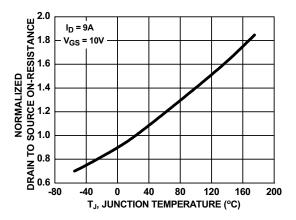


Figure 3. Normalized On Resistance vs Junction Temperature

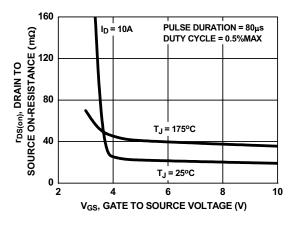


Figure 4. On-Resistance vs Gate to Source Voltage

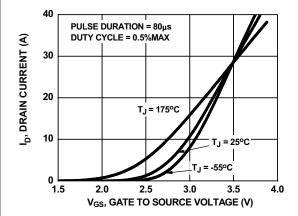


Figure 5. Transfer Characteristics

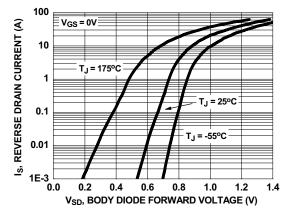
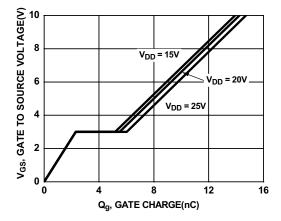


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

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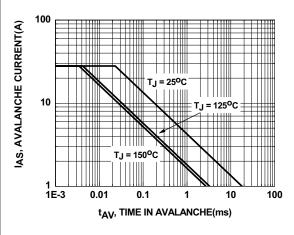
Typical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted



3000 C_{iss} C_{oss} 100 C_{rss} f = 1MHz $V_{GS} = 0V$ $V_{DS}, DRAIN TO SOURCE VOLTAGE (V)$

Figure 7. Gate Charge Characteristics

Figure 8. Capacitance vs Drain to Source Voltage



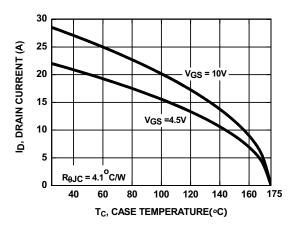
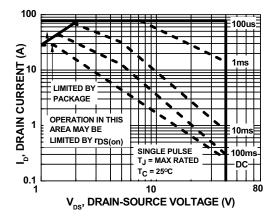


Figure 9. Unclamped Inductive Switching Capability

Figure 10. Maximum Continuous Drain Current vs Case Temperature



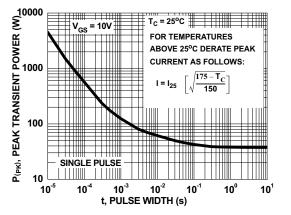


Figure 11. Forward Bias Safe Operating Area

Figure 12. Single Pulse Maximum Power Dissipation

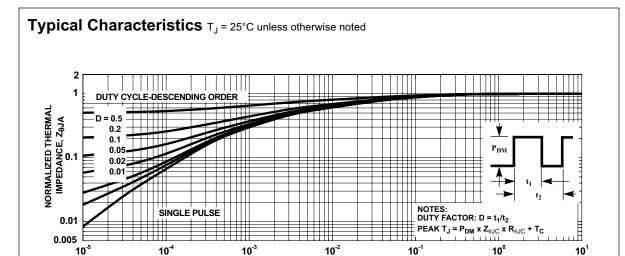
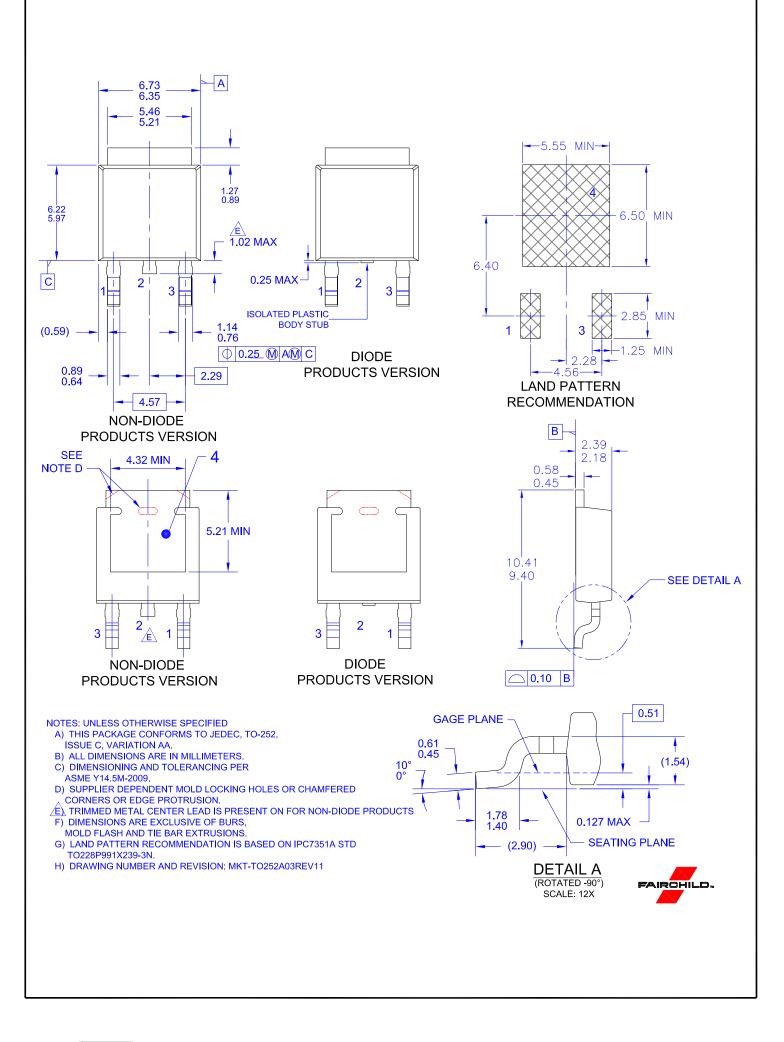


Figure 13. Transient Thermal Response Curve

t, RECTANGULAR PULSE DURATION (s)



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